

Serial No. Not Yet Assigned
Atty. Doc. No. 2003P18131WOUS
ABSTRACT

10/588024

AP20 Rec'd PCT/PTO 01 AUG 2006

The invention relates to a method for repairing components comprising a base material with an oriented microstructure, wherein the repair point comprises a correspondingly oriented microstructure as the surrounding base material. According to the inventive method, solder is applied in the region of a point which is to be repaired and is soldered to the component by means of a heating effect produced by a device. A temperature gradient, i.e., approximately a temperature characteristic, is produced during the heating effect, said temperature characteristic ranging from a high to a low temperature in the region of the point which is to be repaired.